NICHING

Parameter	Test/Measure	Mid Thermal Application			
		DN-1703LM	DN-1705	DN-1715	DN-1718
Curing Temp	degC	175	175	175	175
Viscosity @25deg.C	E-viscometer@5rpm	9,500	8,500	8,000	9,100
Thixotropic Index @25deg.C	0.5rpm/5rpm	5.0	5.2	5.3	4.84
Open Time (for 1*1 mm2 die size)	Hour	4	6	8	3
Volume Resistance	Ohm.cm	4.9*10-5	$4.0*10^{-4}$	$2.4*10^{-5}$	3*10-5
Thermal Conductivity	W/mk	5	2	15	22
Die Shear Strength @25 Deg.C with 2*2 mm Ag BSM Die	On Ag/Cu LF (Mpa)	26	37	30	43
	On Cu PCB (Mpa)	20	45	30	
Die Shear Strength @260 Deg.C 2*2 mm Ag BSM Die	On Ag/Cu LF (Mpa)	10	7	8	5
	On Cu PCB (Mpa)	7	7	8	
Storage Modulus@25 Deg.C	GPa	6	8.7	12	10
Tg	dC	119	73	121	120
CTE	ppm	28/73	40/182	49/160	50/160
Product Benefit		1. Low modulus 2. Good TC	1.Low modulus 2.High adhesion on Ag, Au & Cu finish	1.Good TC 2.Good reliability	1. Good TC 2. Good reliability *DSS is 1*1mm die